Figure 1

Publication	PECVD Reaction	'Delta-n' Control Method	Post-dep. Thermal  Treatment T° (°C)		
Valette S.,1987	Unknown	P doping	Not specified 400°C		
Valette S.,1988	Unknown	P doping			
Grand G., 1990	Unknown	P doping	1000°C		
Liu K., 1995	Unknown	Content in Si, P	Not specified		
Ojha S., 1998	Unknown	Ge, B, or P doping	Not specified		
Canning J., 1998	Unknown	Ge doping	Not specified		
Bulla D., 1998	TEOS	TEOS	Not specified		
Johnson C., 1998	SiH <sub>4</sub> + O,	Si ion Implantation	400°C		
Boswell R. W., 1997	$SiH_4 + O_2$	SiH <sub>4</sub> /O, flow ratio	1000°C		
Bazylenko M. V., 1995	$SiH_4 + O_2 + CF_4$	(SiH <sub>4</sub> +O <sub>2</sub> )/CF <sub>4</sub> flow ratio	Not specified		
Bazylenko M. V., 1996	$SiH_4 + O_2 + CF_4$	(SiH <sub>4</sub> +O <sub>2</sub> )/CF <sub>4</sub> flow ratio	1000°C		
Durandet A., 1996	$SiH_4 + O_2 + CF_4$	SiH <sub>4</sub> /O <sub>2</sub> /CF <sub>4</sub> flow ratio	100°C		
Kapser K., 1991	SiH <sub>4</sub> + N <sub>2</sub> O	SiH <sub>4</sub> /N <sub>2</sub> O flow ratio	1060°C		
Lai Q., 1992	SiH <sub>4</sub> + N <sub>2</sub> O	SiH <sub>4</sub> /N <sub>2</sub> O flow ratio	1100°C		
Lai Q.,1993	$SiH_4 + N_2O$	SiH <sub>4</sub> /N <sub>2</sub> O flow ratio	1100°C		
Pereyra I., 1997	SiH <sub>4</sub> + N <sub>2</sub> O	SiH <sub>4</sub> /N <sub>2</sub> O flow ratio	400°C		
Alayo M., 1998	$SiH_4 + N_2O$	SiH <sub>4</sub> /N <sub>2</sub> O flow ratio	1000°C		
Pereyra I., 1997  Alayo M., 1998  Kenyon T., 1997	$SiH_4 + N_2O + Ar$	SiH <sub>4</sub> /N <sub>2</sub> O/Ar flow ratio	1000°C		
	$SiH_4 + N_2O + NH_3$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> flow ratio	Not specified		
Bruno F., 1991  Vokoberno S. 1995	$SiH_4 + N_2O + NH_3$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> flow ratio	1100°C		
Yokohama S., 1995	$SiH_4 + N_2O + NH_3$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> flow ratio	Not specified		
Agnihotri O. P., 1997	$SiH_4 + N_2O + NH_3$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> flow ratio	700-900°C		
Ocimann K., 1999	$SiH_4 + N_2O + NH_3$	Unknown	1100°C		
Offrein B., 1999	$SiH_4 + N_2O + NH_3$	Unknown	1150°C		
Offrein B., 1999 Hoffmann M., 1995 Hoffmann M., 1997	$SiH_4 + N_2O + NH_3 + Ar$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> /Ar flow ratio	Not specified		
Hoffmann M., 1997	$SiH_4 + N_2O + NH_3 + Ar$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> /Ar flow ratio	Not specified		
	$SiH_4 + N_2O + NH_3 + N_2$	$N_2O/(N_2O + NH_3)$ flow ratio	1050°C		
Poenar D., 1997	$SiH_4 + N_2O + NH_3 + N_2$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> /N <sub>2</sub> flow ratio	850°C		
Poenar D., 1997  Ridder R., 1998	$SiH_4 + N_2O + NH_3 + N_2$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>4</sub> /Ar flow ratio	1100°C		
Worhoff K., 1999	$SiH_4 + N_2O + NH_3 + N_2$	SiH <sub>4</sub> /N <sub>2</sub> O/NH <sub>3</sub> /N <sub>2</sub> flow ratio	1150°C		
Bulat E.S., 1993	$SiH_4 + N_2O + N_2 + O_2 + He + CF_4$	SiH <sub>4</sub> /(N <sub>2</sub> O/N <sub>2</sub> )/O <sub>2</sub> /CF <sub>4</sub> flow ratio	425°C		
This Patent Application	$SiH_4 + N_2O + PH_3 + N_2$	Patented Pending Method	650°C		

Figure 2

			н-он	SiO-H	H-NiS	H-N:IS	Si-H	Si=O	NEN	Si-O-Si	Si-O-Si	Si-ON	Si-OH	Si-O-is	Si-0-Si
2000															
	œ돠용후	Min	3550	3470	3380	3300	2210	1800	1530	1080	1000	910	860	740	410
	FTIR 1st mode (cm-1)	Ave	3650	3510	3420	3380	2260	1875	1555	1180	1080	950	885	810	460
		Max	3750	3550	3460	3460	2310	1950	1580	1280	1160	990	910	880	510
	+ <del>8</del> (=	Min	2.817	2.882	2.959	3.030	4.525	5.556	6.536	9.259	10.000	10.989	11.628	13.514	24.390
	1st mode (µm)	Ave	2.740	2.849	2.924	2.959	4.425	5.333	6.431	8.475	9.259	10.526	11.299	12.346	21.739
		Max	2.667	2.817	2.890	2.890	4.329	5.128	6.329	7.813	8.621	10.101	10.989	11.364	19.608
	- g e ←	Min	1.408	1.441	1.479	1.515	2.262	2.778	3.268	4.630	5.000	5.495	5.814	6.757	12.195
	2nd mode (µm)	Ave	1.370	1.425	1.462	1.479	2.212	2.667	3.215	4.237	4.630	5.263	5.650	6.173	10.870
		Max	1.333	1.408	1.445	1.445	2.165	2.564	3.165	3.906	4.310	5.051	5.495	5.682	9.804
	3rd mode (µm)	Min	0.939	0.961	0.986	1.010	1.508	1.852	2.179	3.086	3.333	3.663	3.876	4.505	8.130
	25 E	Ave	0.913	0.950	0.975	0.986	1.475	1.778	2.144	2.825	3.086	3.509	3.766	4.115	7.246
	-	Max	0.889	0.939	0.963	0.963	1.443	1.709	2.110	2.604	2.874	3.367	3.663	3.788	6.536
	c#6	Min	0.704	0.720	0.740	0.758	1.131	1.389	1.634	2.315	2.500	2.747	2.907	3.378	6.098
	4th mode (µm)	Ave	0.685	0.712	0.731	0.740	1.106	1.333	1.608	2.119	2.315	2.632	2.825	3.086	5.435
		Max	0.667	0.704	0.723	0.723	1.082	1.282	1.582	1.953	2.155	2.525	2.747	2.841	4.902
	- <del>2</del> = -	Min	0.563	0.576	0.592	0.606	0.905	1.111	1.307	1.852	2.000	2.198	2.326	2.703	4.878
	5th mode (µm)	Ave	0.548	0.570	0.585	0.592	0.885	1.067	1.286	1.695	1.852	2.105	2.260	2.469	4.348
	<u> </u>	Max	0.533	0.563	0.578	0.578	0.866	1.026	1.266	1.563	1.724	2.020	2.198	2.273	3.922
	- <del>2</del> <del>2</del> <del>2</del>	Min	0.469	0.480	0.493	0.505	0.754	0.926	1.089	1.543	1.667	1.832	1.938	2.252	4.065
	6th mode (µm)	Ave	0.457	0.475	0.487	0.493	0.737	0.889	1.072	1.412	1.543	1.754	1.883	2.058	3.623
	-	Max	0.444	0.469	0.482	0.482	0.722	0.855	1.055	1.302	1.437	1.684	1.832	1.894	3.268
	a) de	Min	0.402	0.412	0.423	0.433	0.646	0.794	0.934	1.323	1.429	1.570	1.661	1.931	3.484
	7th mode (µm)	Ave	0.391	0.407	0.418	0.423	0.632	0.762	0.919	1.211	1.323	1.504	1.614	1.764	3.106
	_	Max	0.381	0.402	0.413	0.413	0.618		0.904	1.116	1.232	1.443	1.570	1.623	2.801
	그윽	Min	0.352	0.360	0.370	0.379	0.566	0.694	0.817	1.157	1.250	1.374	1.453	1.689	3.049
**	8th mode (µm)	Ave	0.342	0.356	0.365	0.370	0.553	0.667	0.804	1.059	1.157	1.316	1.412	1.543	2.717
		Max	0.333	0.352	0.361	0.361	0.541	0.641	0.791	0.977	1.078	1.263	1.374	1.420	2.451

The graph of the species of the spec

Figure 3a

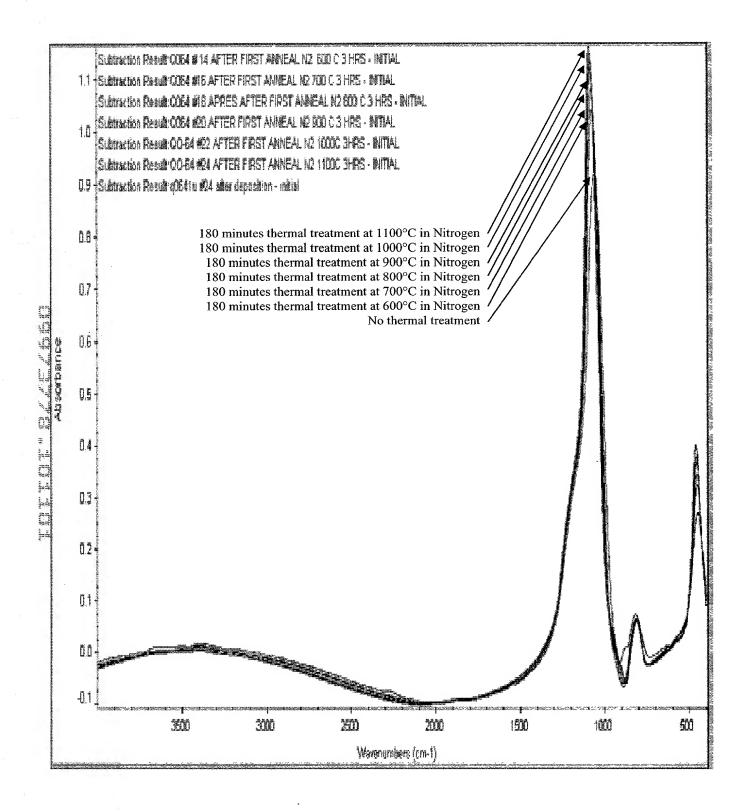


Figure 3b

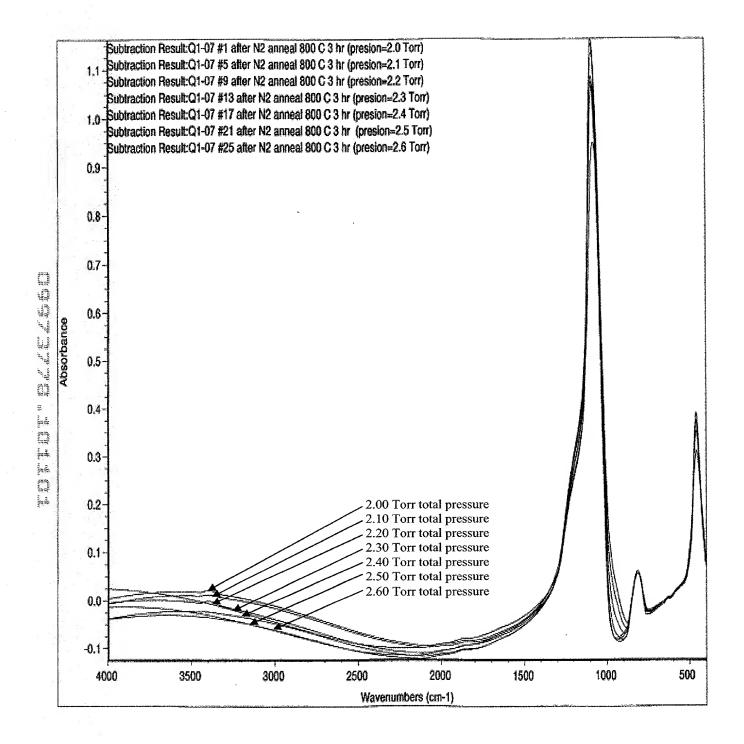
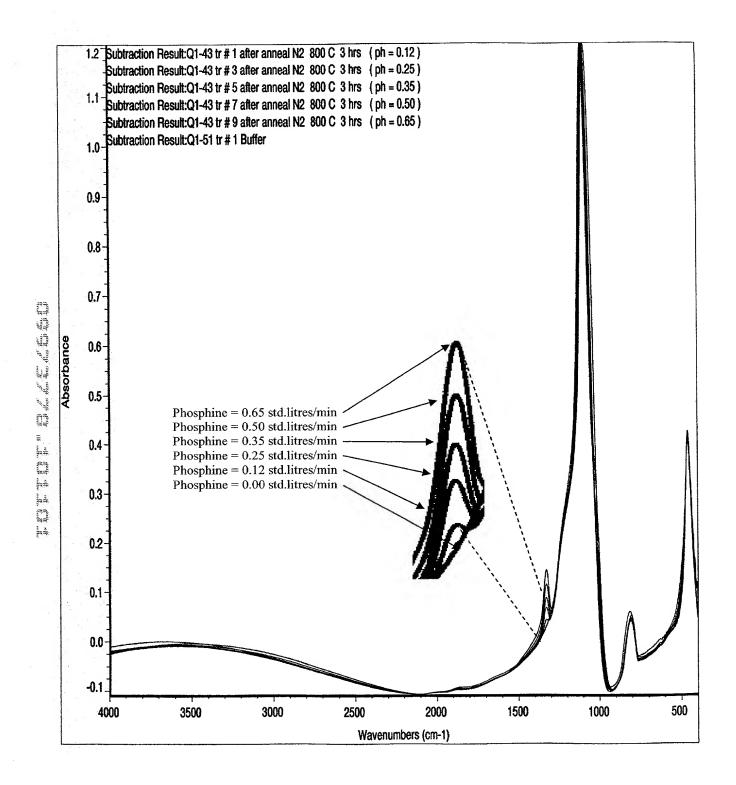


Figure 3c



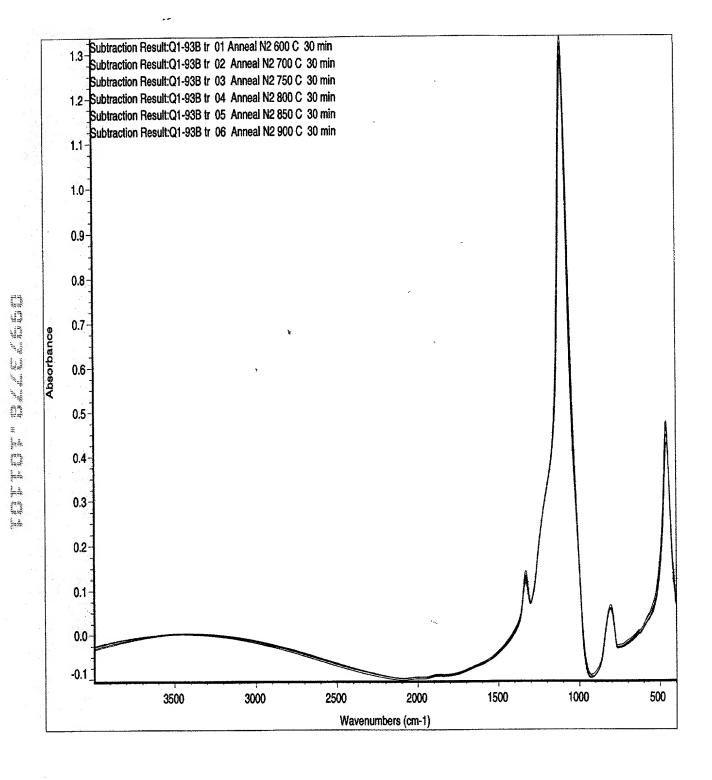


Figure 4a

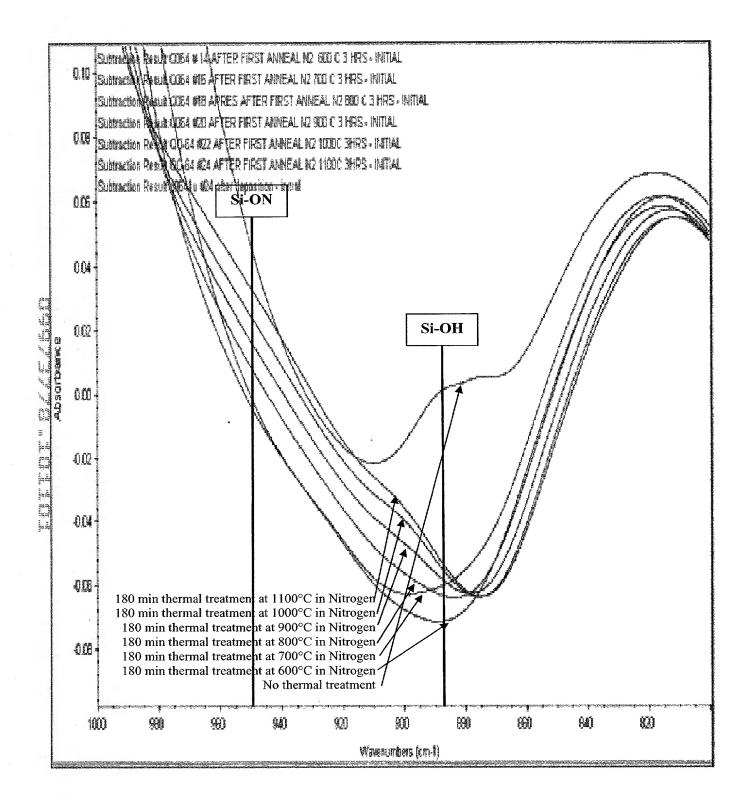


Figure 4b

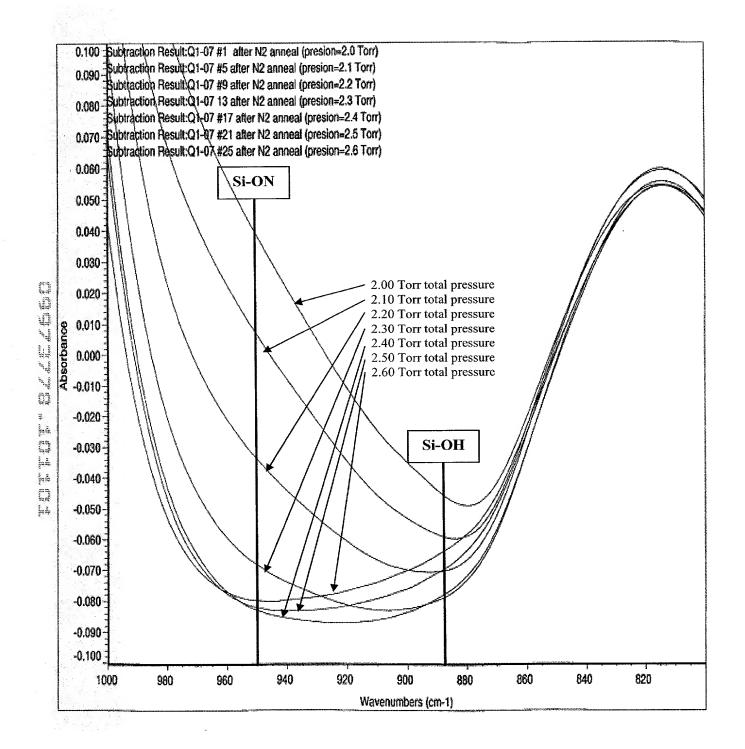
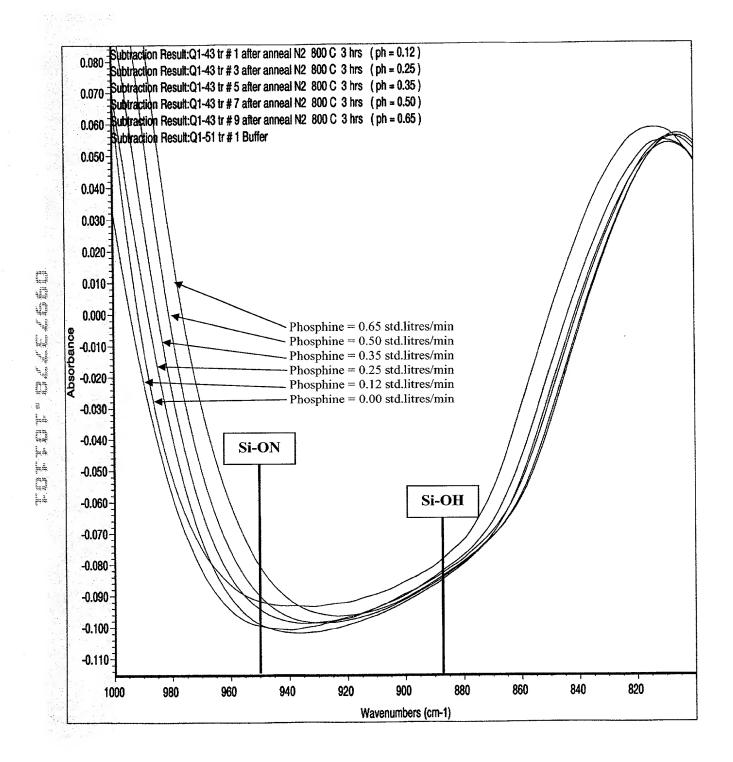
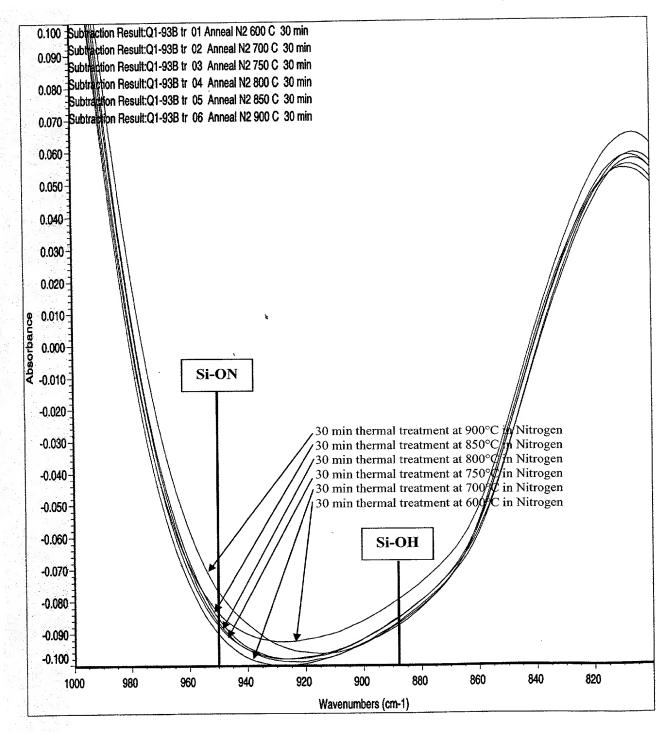
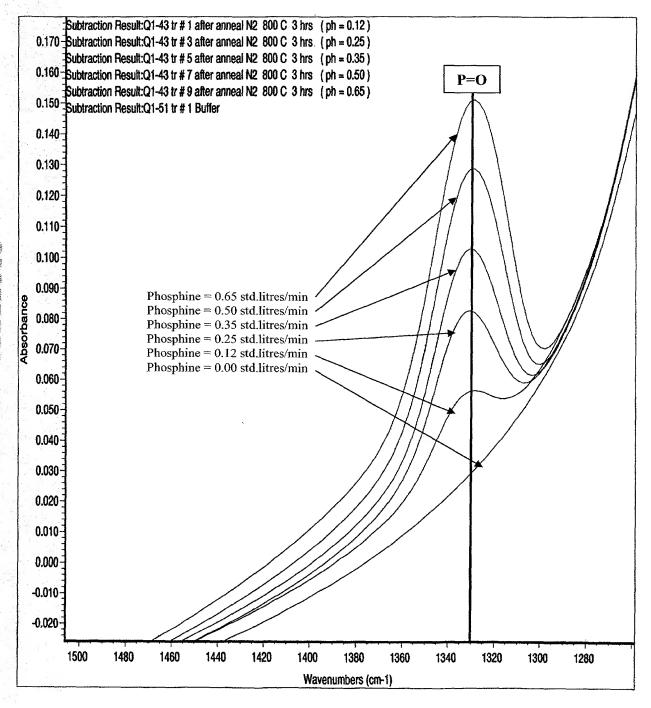


Figure 4c









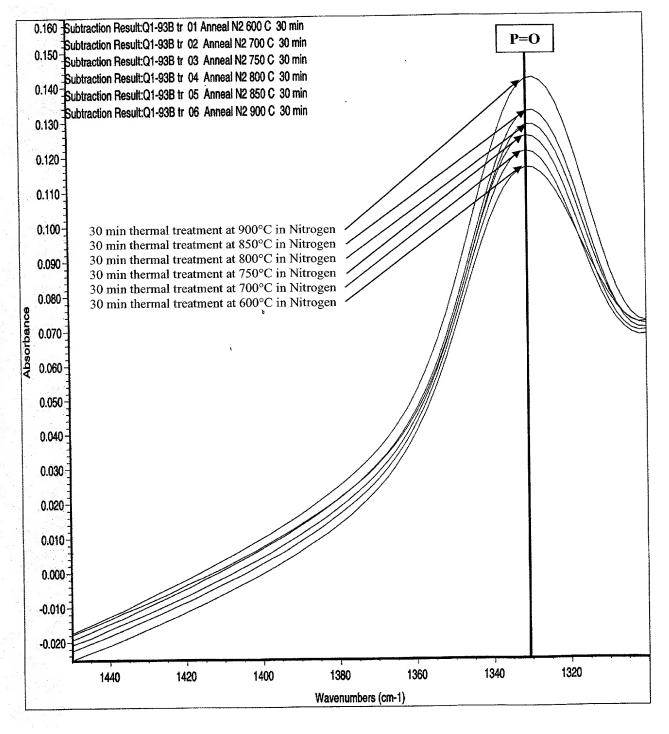


Figure 6a

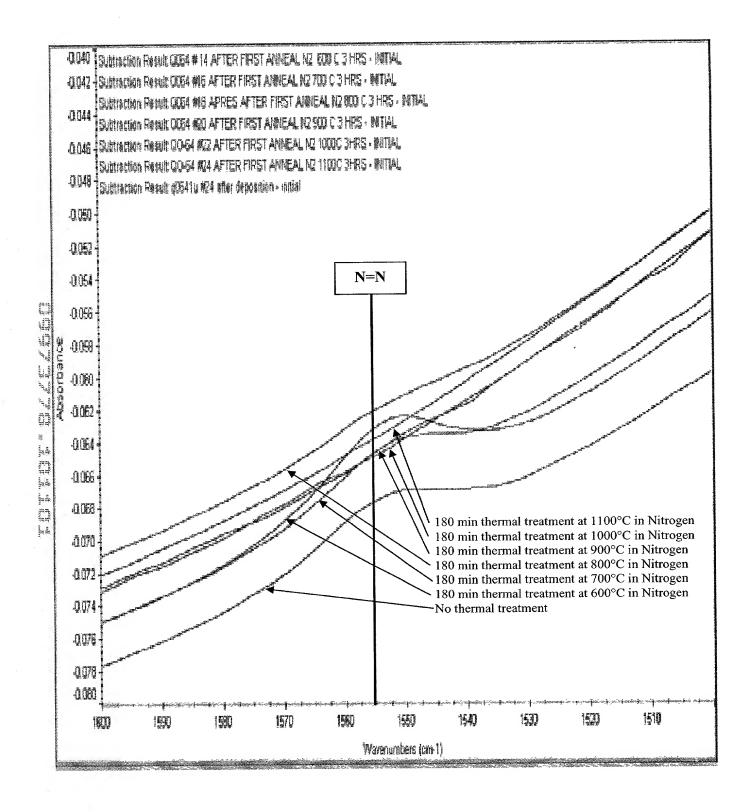


Figure 6b

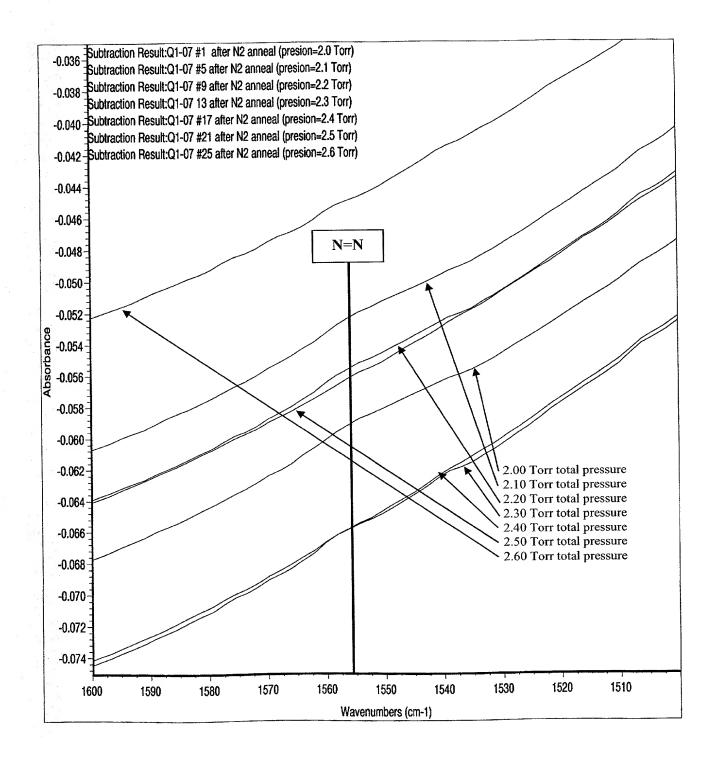
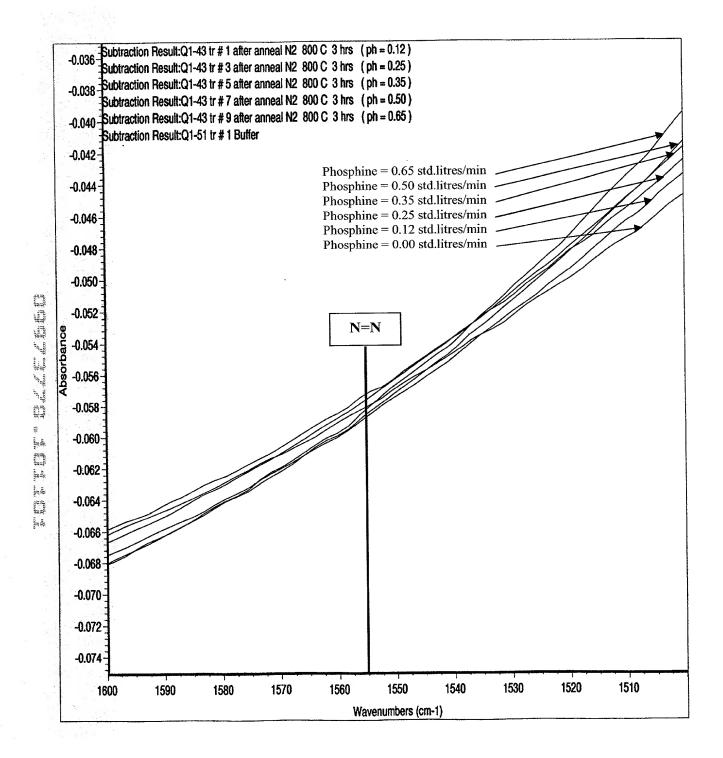


Figure 6c



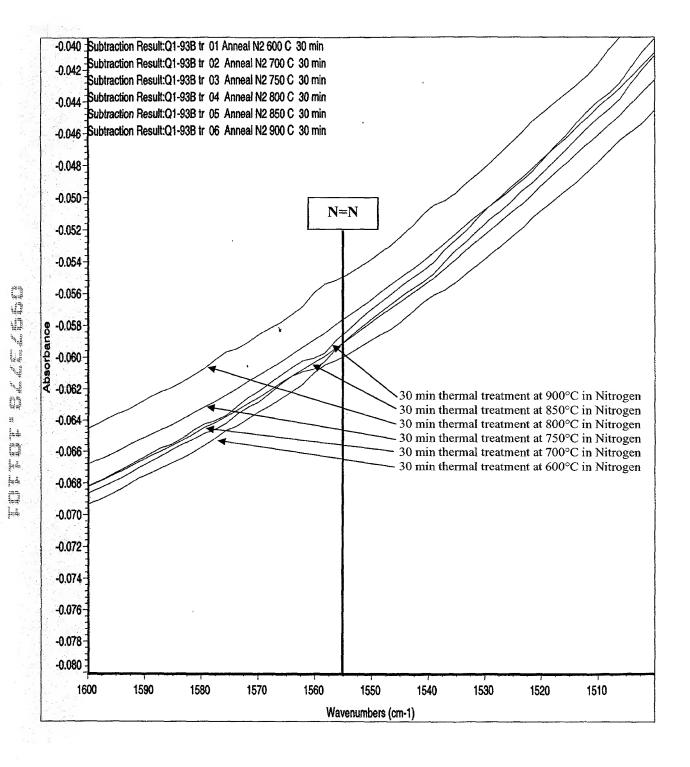


Figure 7a

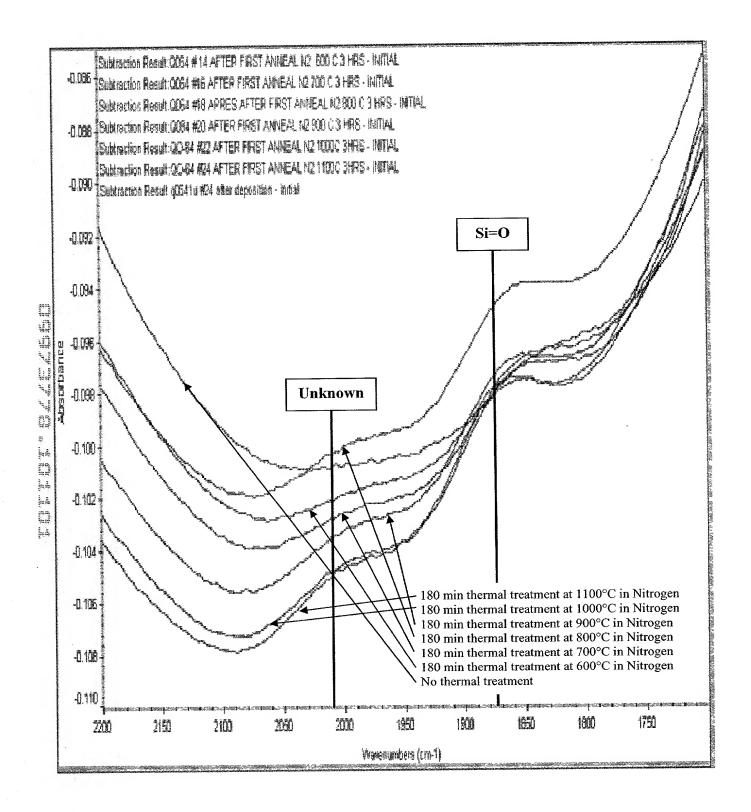
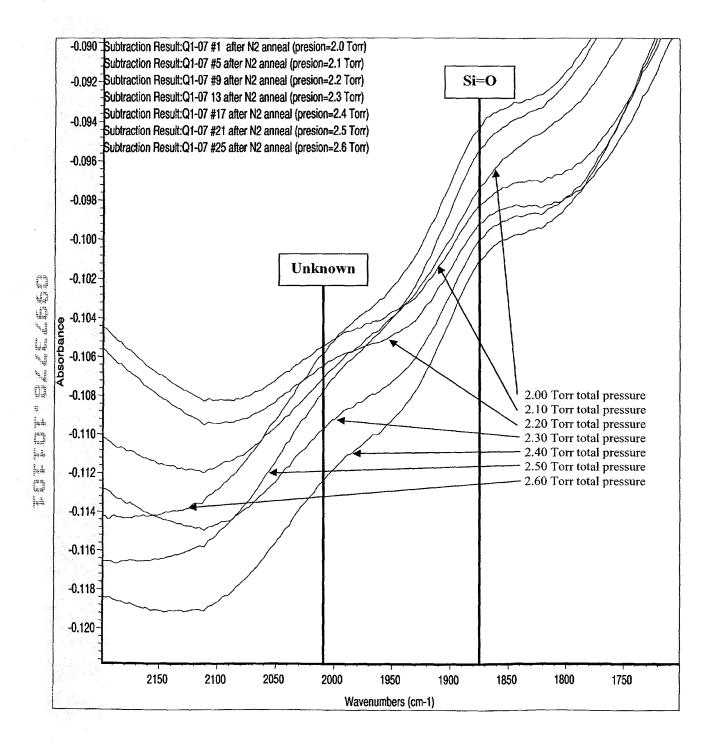
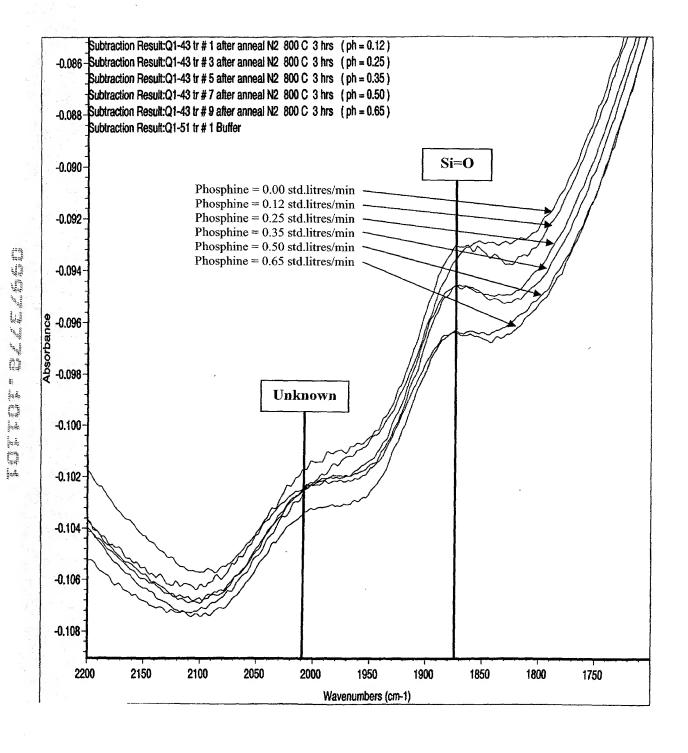


Figure 7b





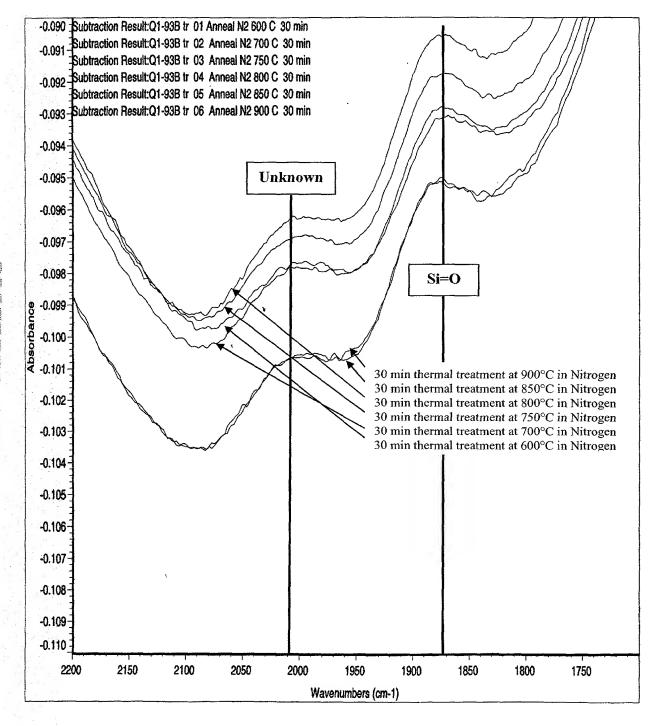


Figure 8a

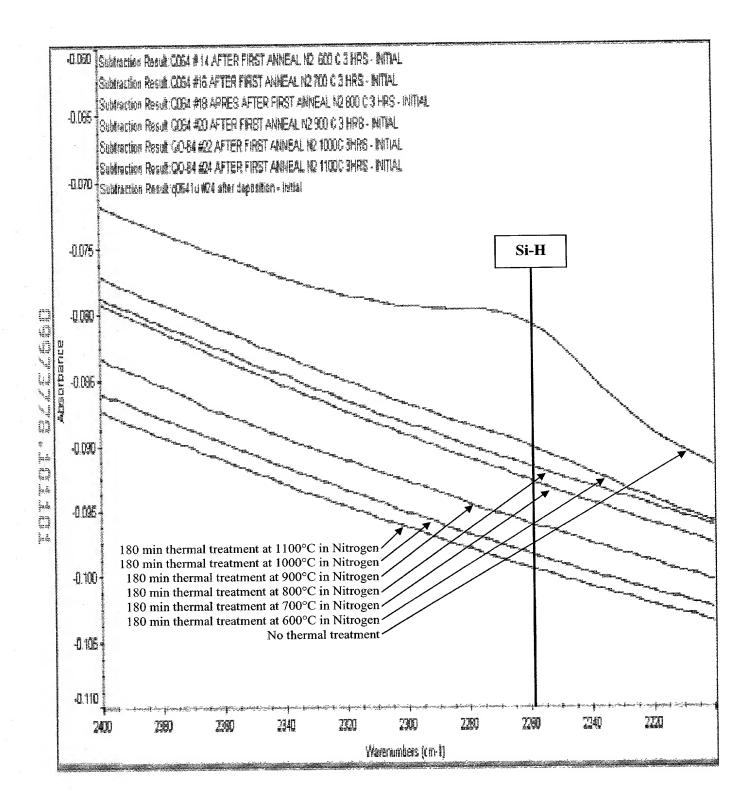


Figure 8b

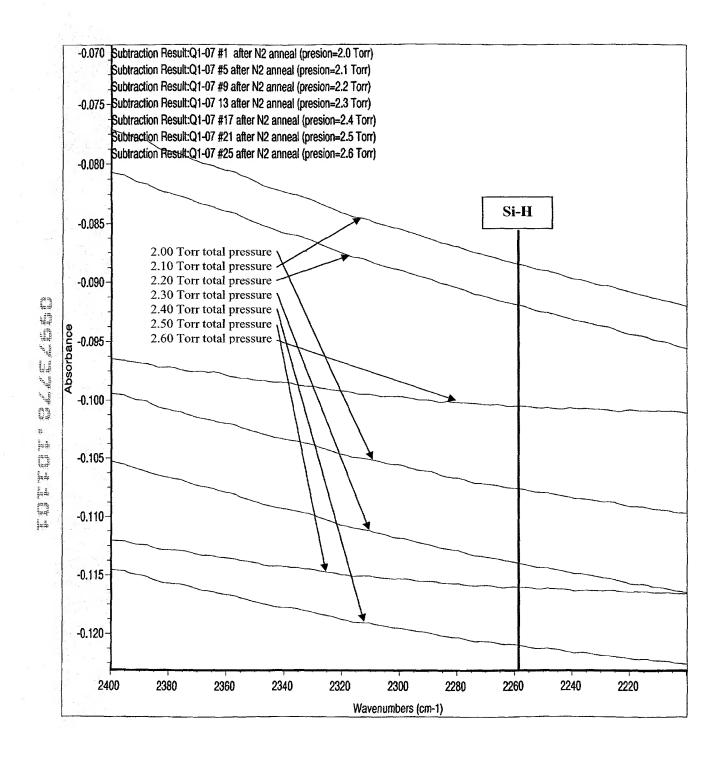


Figure 8c

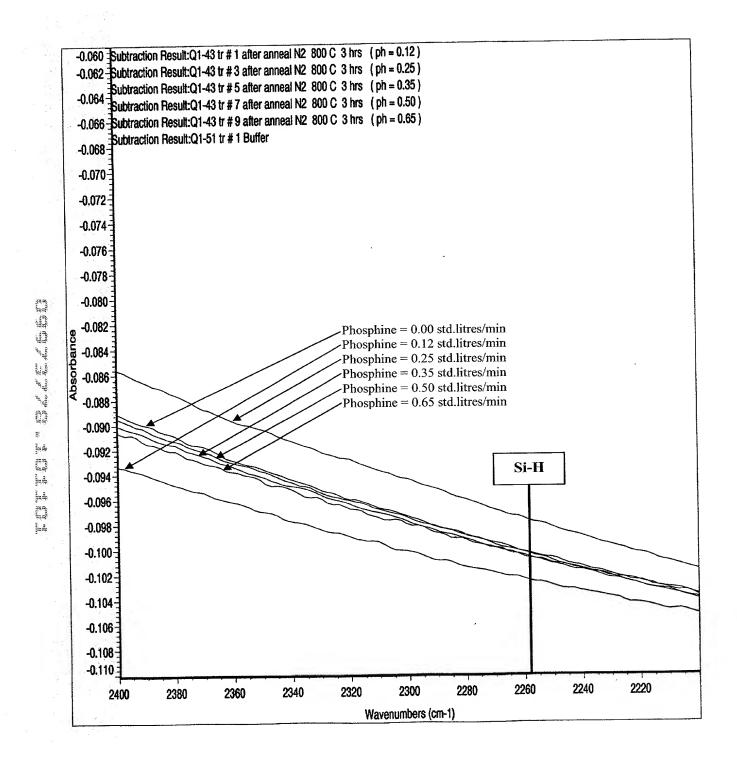


Figure 8d

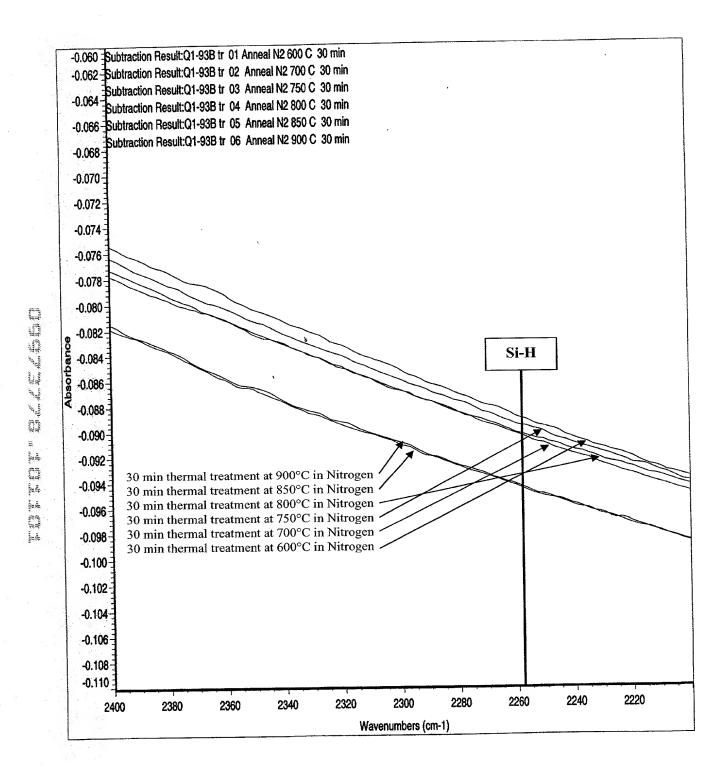


Figure 9a

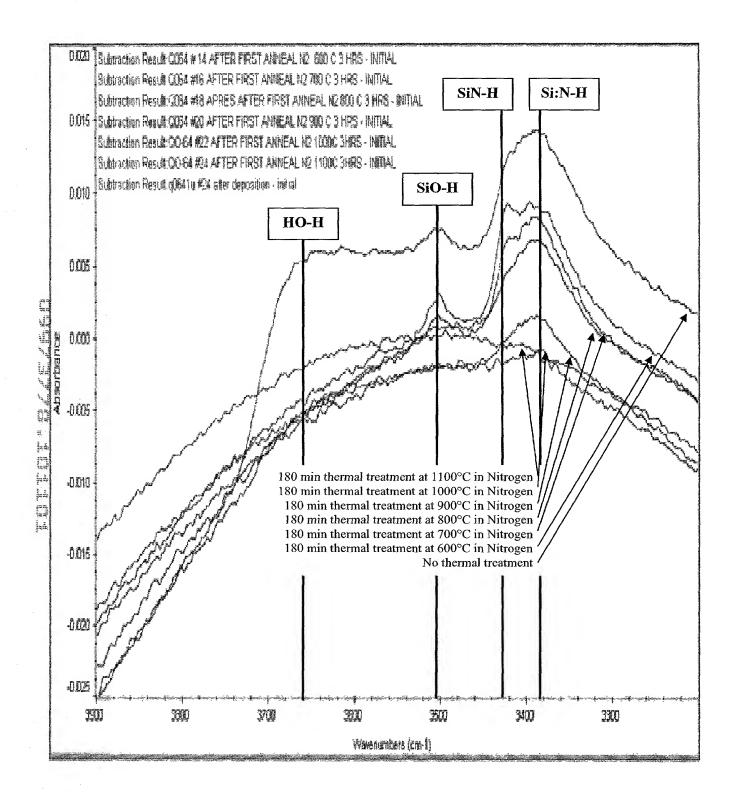
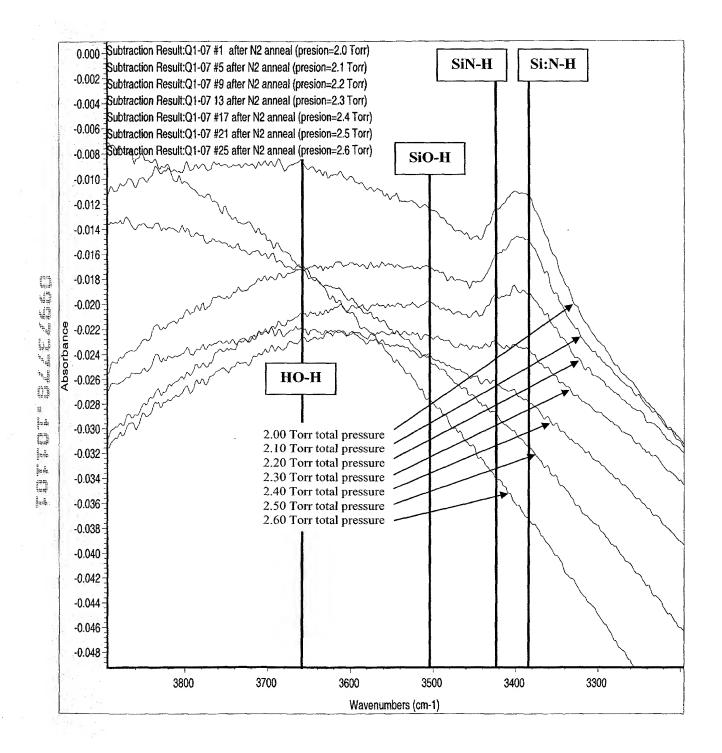


Figure 9b



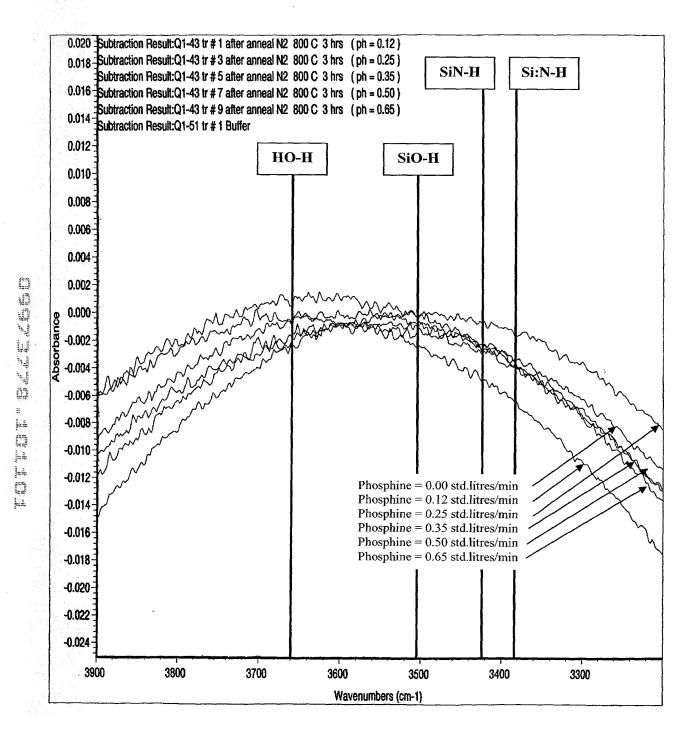


Figure 9d

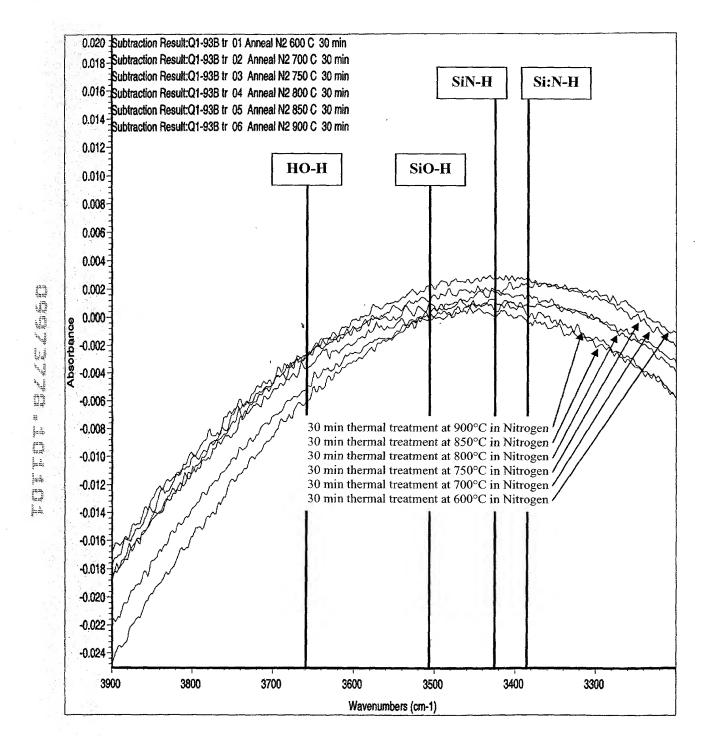
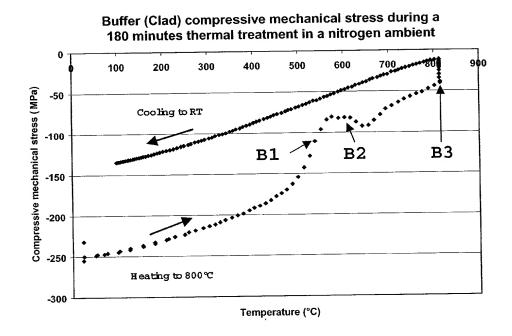


Figure 10



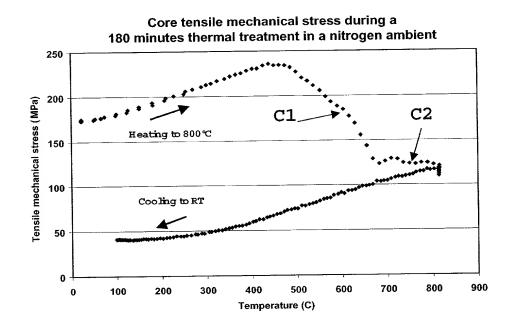
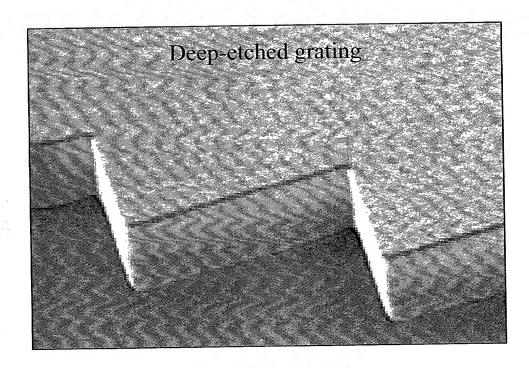


Figure 11



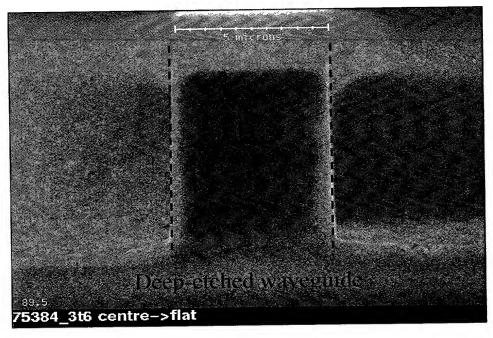


Figure 12

**Tensile stress Core** 

(Core wants to contract)

Desired vertical deep-etched profile

Compressive stress Buffer (Clad)

(Buffer (Clad) wants to expand)

Tensile stress Core (Core wants to contract)

Desired vertical deep-etched profile

Compressive stress Buffer (Clad) (Buffer (Clad) wants to expand)

Tensile stress Core

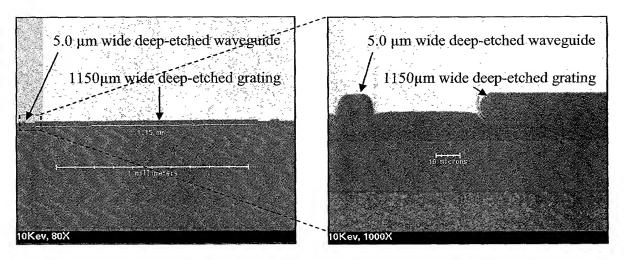
(Core wants to contract)

Desired vertical deep-etched profile

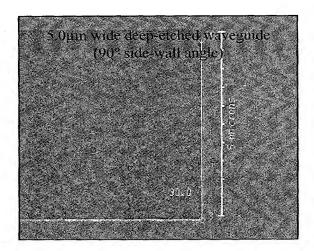
Compressive stress Buffer (Clad)

(Buffer (Clad) wants to expand)

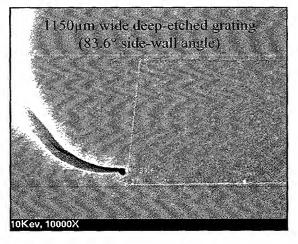
Figure 13



The relative position between an isolated 5.0µm wide deep-etched waveguide and its neighboring 1150µm wide deep-etched grating at two different magnifications.

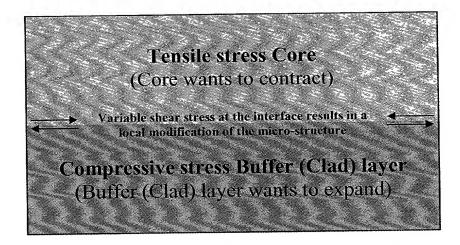


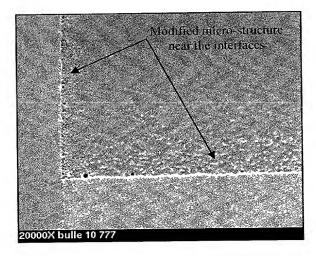
The side-wall of the 5.0µm wide deepetched waveguide facing the neighboring grating has a slope of about 90°.



The side-wall of the 1150µm wide deepetched grating facing the neighboring deep-etched waveguide has a much smaller slope of about 84°.

Figure 14





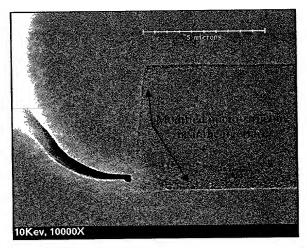
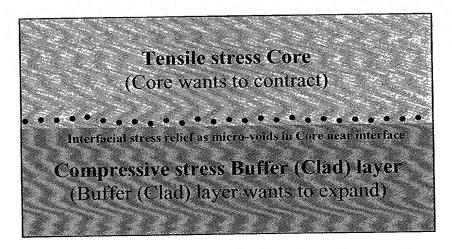
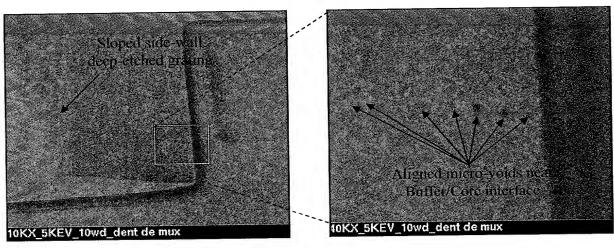


Figure 15





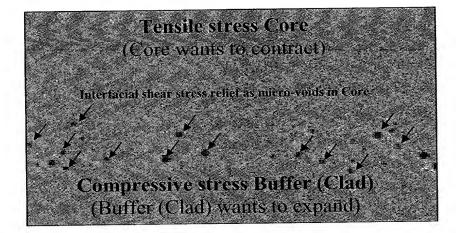
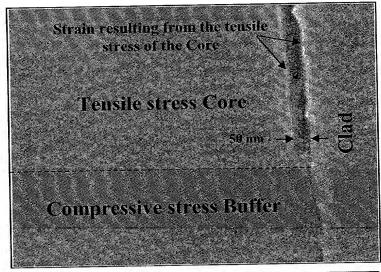


Figure 16



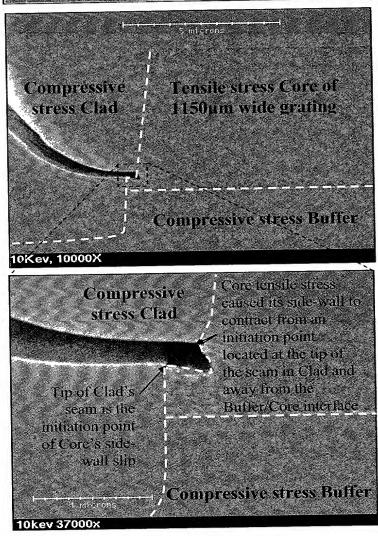
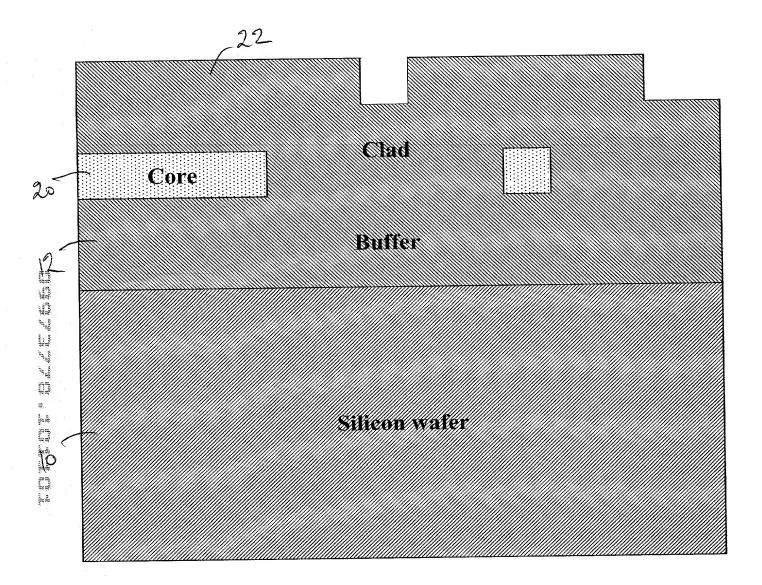


Figure 17



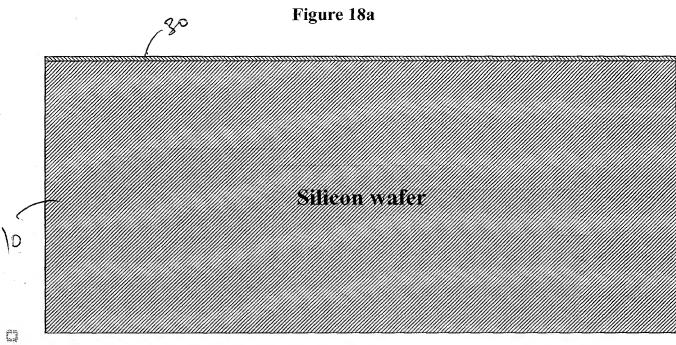


Figure 18b

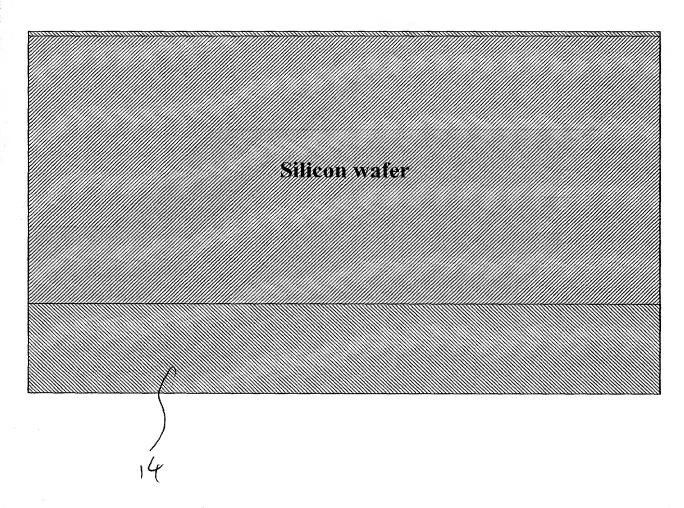
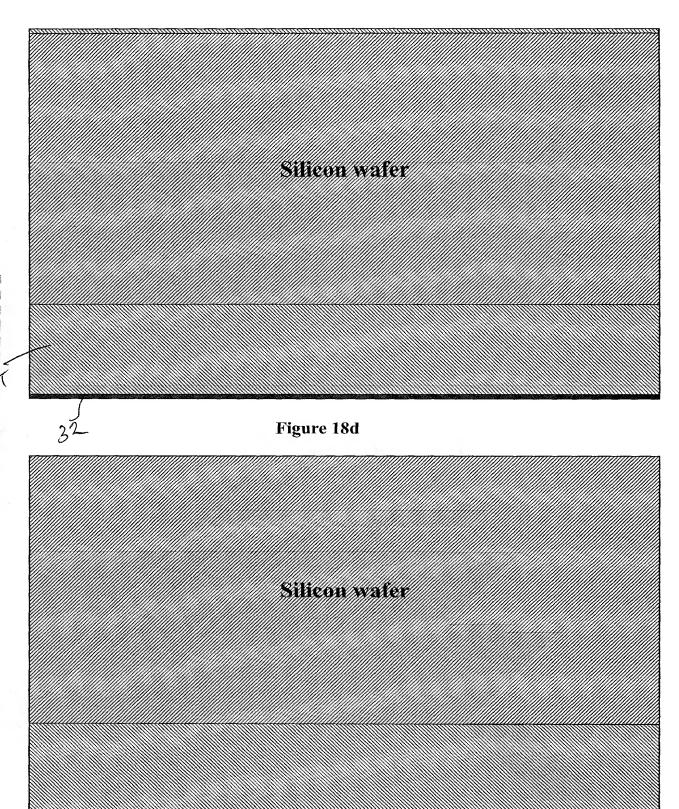


Figure 18c



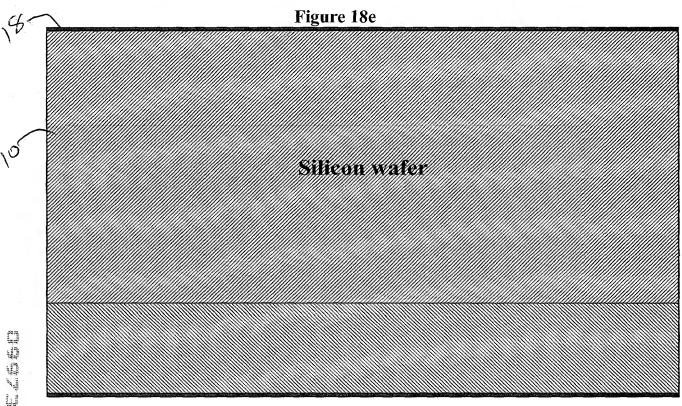


Figure 18f

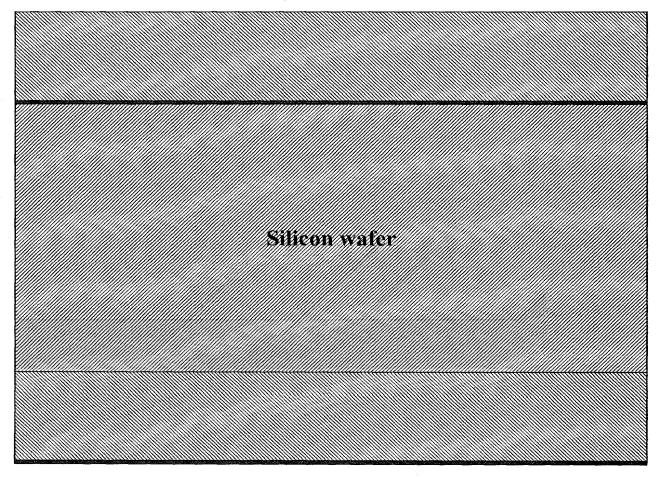


Figure 18g

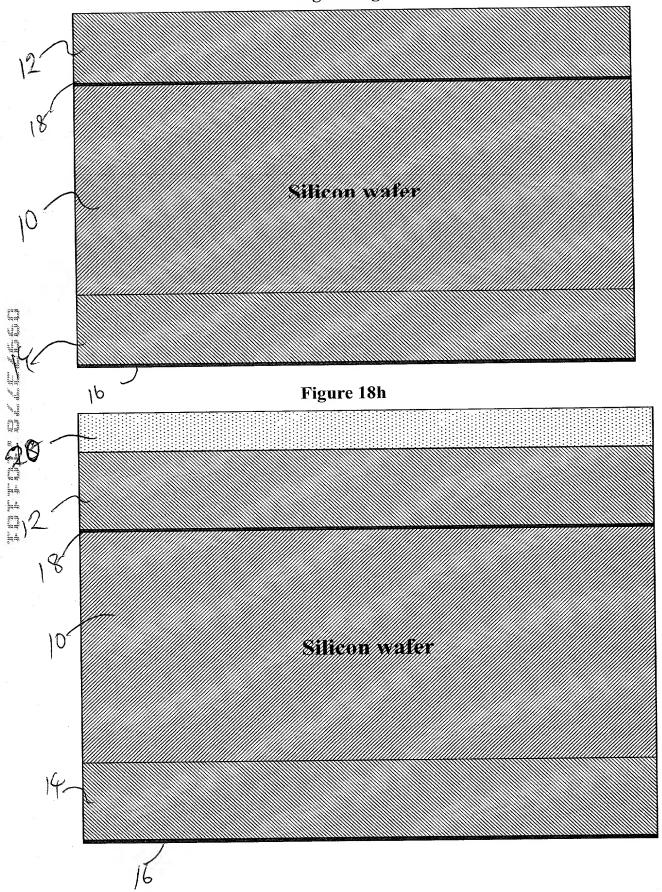
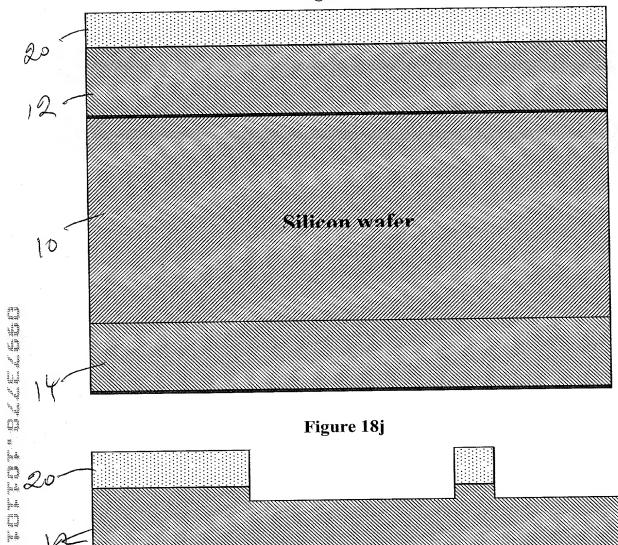
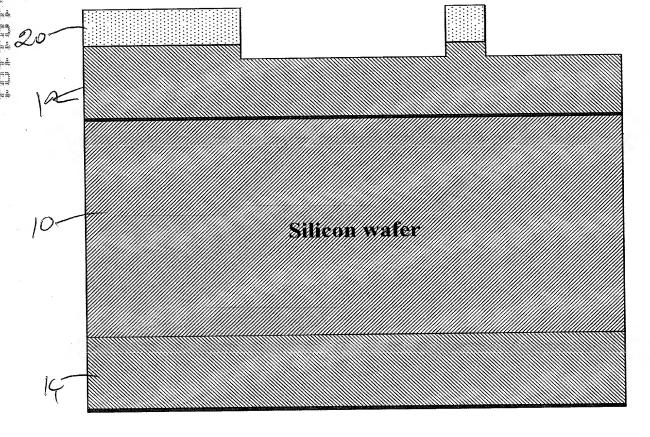


Figure 18i







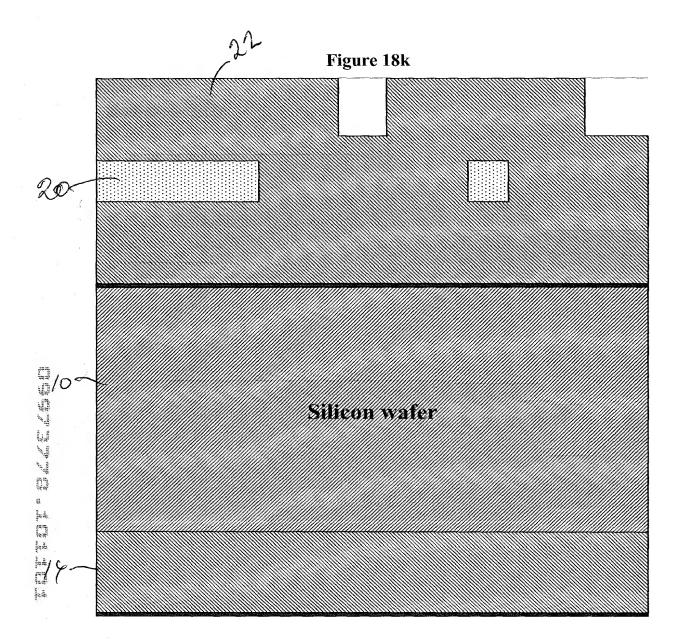


Figure 181

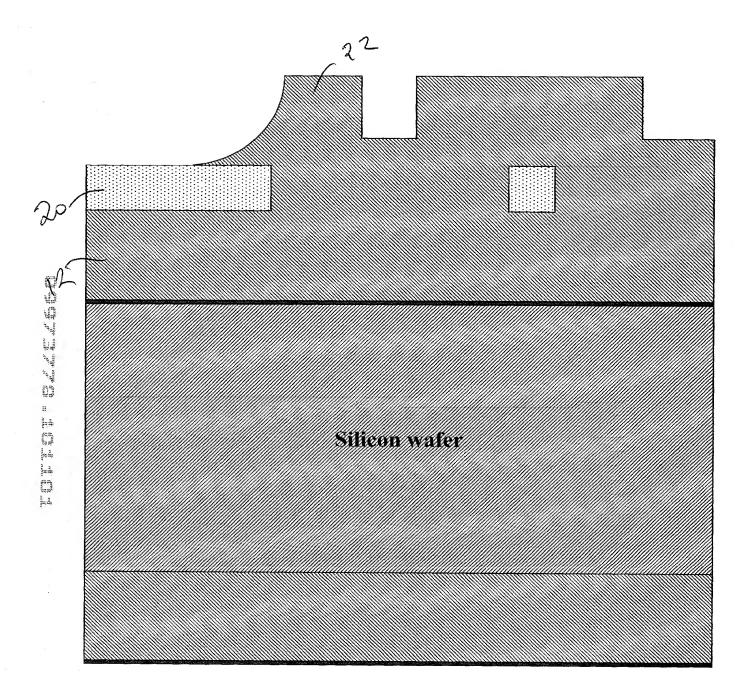


Figure 19

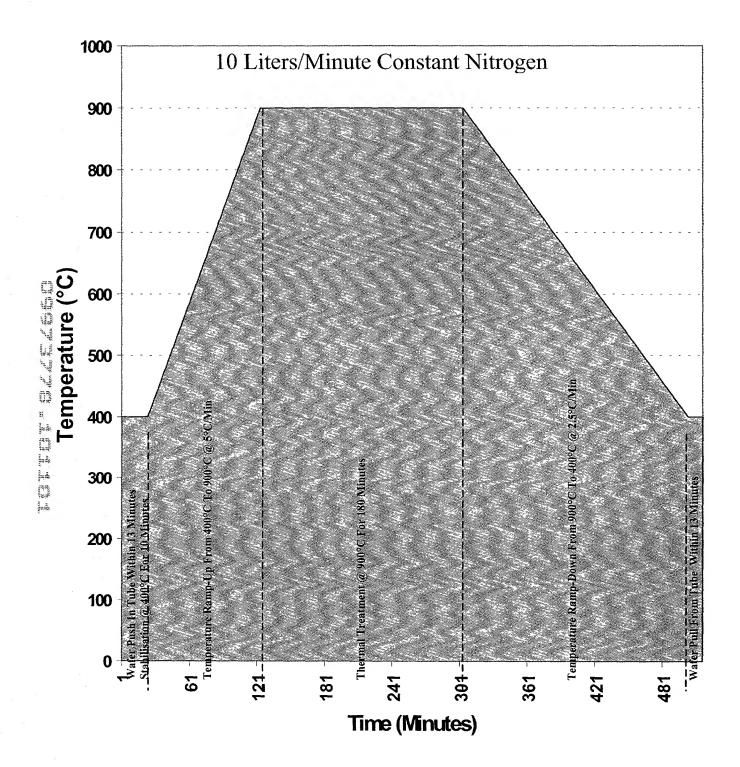


Figure 20

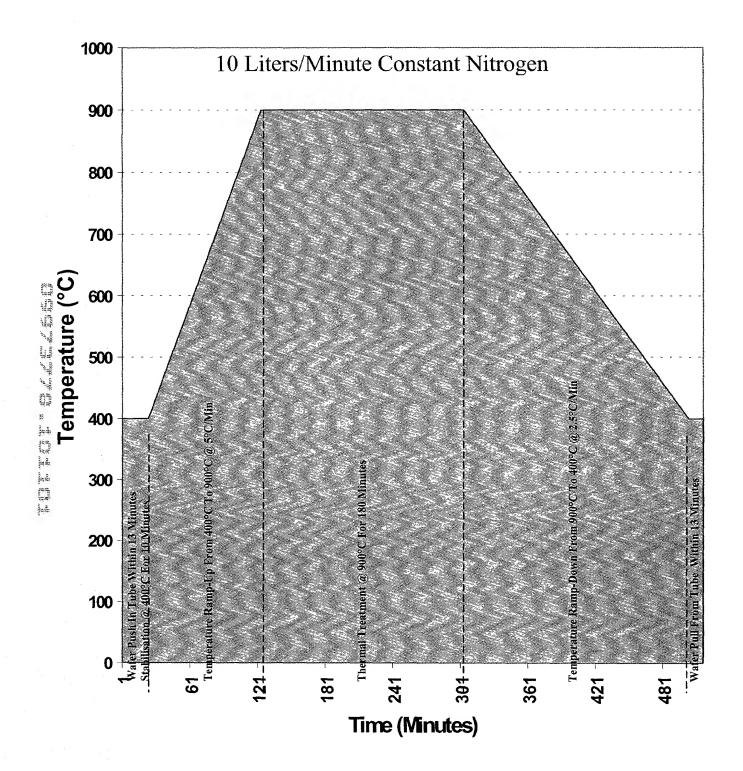


Figure 21

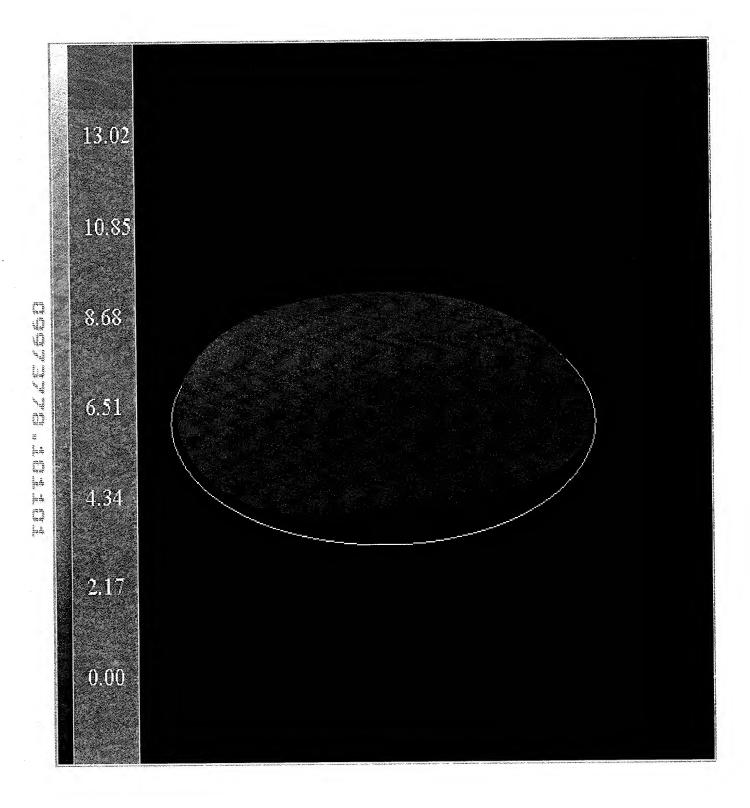


Figure 22

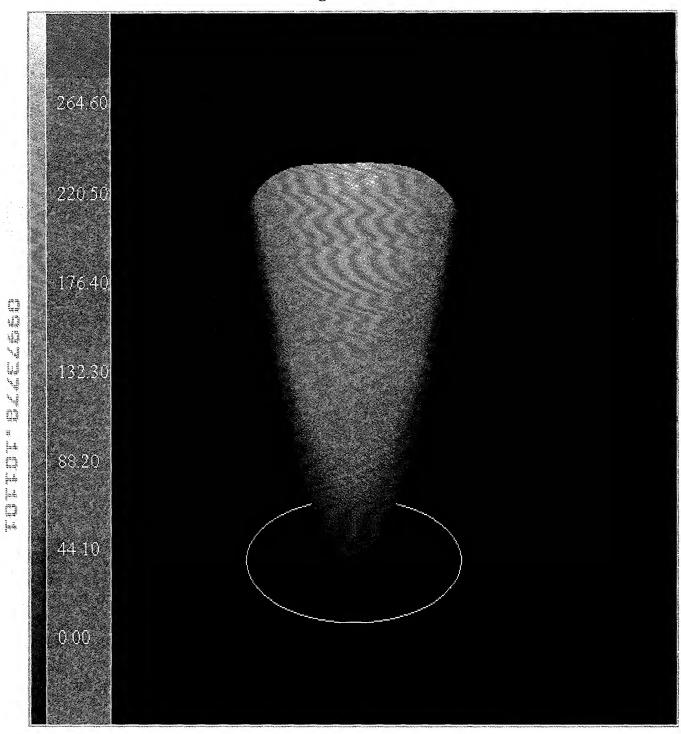


Figure 23

